

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



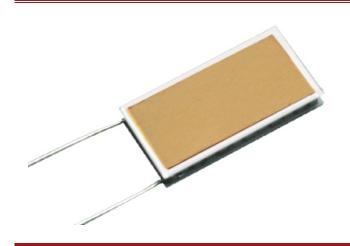






Technical Data Sheet for CM35-1.9

Commercial Module for CATV & SLED Applications



NOMINAL PERFORMANCE IN NITROGEN

Hot Side Temperature (°C)	27	85
Δ Tmax (°C):	71	92
Qmax (watts):	5.2	6.2
Imax (amps):	1.9	1.8
Vmax (vdc):	4.2	5.3
AC Resistance (ohms):	1.87	

PRODUCT FEATURES

- RoHS EU Compliant
- Ceramic Material: Aluminum Oxide (AC) or Aluminum Nitride (AN)
- Au flash exterior, suitable for soldering.
- Maximum process temperature is 220°C.
- Height includes metallization, where applicable, and excludes tinning.

ORDERING OPTIONS

Model Number	Description
CM35-1.9-01AC	TEM, Top and Base Metallized
	Exterior, ALO Ceramics
CM35-1.9-04AC	-01AC, Top and Base Pre-Tinned
	w/146°C Solder
CM35-1.9-05AC	-01AC, Top and Base Pre-Tinned
	w/138°C Solder
CM35-1.9-06AC	-01AC, Top and Base Pre-Tinned
	w/183°C Solder
CM35-1.9-07AC	-01AC, Top and Base Pre-Tinned
	w/118°C Solder
CM35-1.9-08AN	TEM, Top and Base Metallized
	Exterior, ALN Ceramics
CM35-1.9-09AN	TEM, No Metallized Exterior, ALN
	Ceramics
	A solution

OPERATION CAUTIONS

For maximum reliability, storage and operation below 85°C in a non-condensing environment is recommended. To minimize thermal stress, use linear/proportional temperature control or a similar method rather than an ON/OFF method.

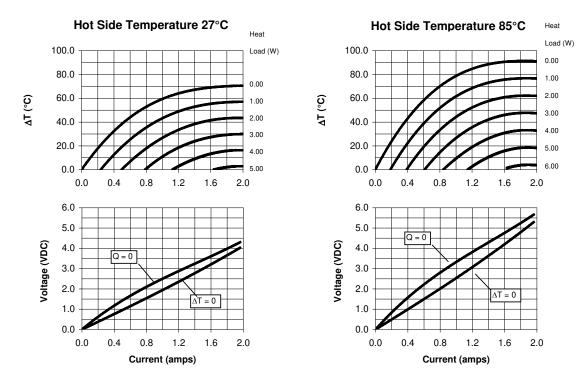
INSTALLATION

Recommended mounting methods: Bonding with thermal epoxy or soldering with metallized ceramics. For additional information, please refer to our TEC Installation Guide.

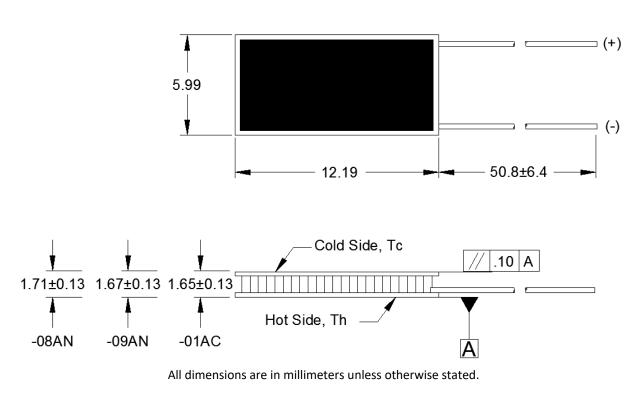
II-VI Marlow – Dallas, TX USA 214-340-4900 877-627-5691 marlow.sales@ii-vi.com Marlow Industries Europe GmbH - Germany +49 (0) 6150 5439 - 403 info@marlow-europe.eu II-VI Japan Inc. 81 43 297 2693 (tel) center@ii-vi.co.jp www.ii-vi.co.jp II-VI Singapore Pte., Ltd. (65) 6481 8215 (tel) info@ii-vi.com.sg Marlow Industries China, II-VI Technologies Beijing 86-10-643 98226 info@iivibj.com

MARLOW MATERIALS THAT MATTER

ENVIRONMENT: ONE ATMOSPHERE DRY NITROGEN



For performance information in a vacuum or with hot side temperatures other than 27°C or 85°C, contact one of our Applications Engineers at 877-627-5691.



For customer support or general questions please contact a local office or visit our website at www.marlow.com